



MEMS LGA

MEMS Microphon

DESCRIPTION

Lingsen MEMS Microphone is a wire bonded and cap seal on substrate system in package. It will possess light, thin, short and small advantage. MEMS(Micro Electro-Mechanical system) Microphone can be used in communication and consumption products etc..

SPECIFICATIONS

◆ Gold Wire	99.99% Au
◆ Cap	Plastic and Metal
◆ Marking	Laser Mark
◆ Packing	Tray

APPLICATIONS

- Note-Book、Multimedia Monitor
- Cellular Phone 、Bluetooth、Hearing Aid

FEATURES

- Miniaturization
- Automatic assembly
- Full in-house design and test capability

RELIABILITY

MSL JEDEC Level 3C@260°C

High Temperature Storage 168hrs(105°C)

Low Temperature Storage 168hrs(-40°C)

Temperature & Humidity 168hrs(60°C,60%RH)

Thermal Shock Test 100 cycles(-40/125°C, 15min soaks < 30sec ramps)

Mechanical Shock Test 10,000 G shocks, 5 impacts along each of 6 axes

Vibration Test Sinusoidal vibration, 20-2000Hz, 4min sweeps, 16min along each of 3axes, amplitude limits of 20G and 0.06"

Electro Static Discharge Human body model, ±2000V Machine model, ±200V

ELECTRO-ACOUSTIC PERFORMANCE

MMI C0064737T(4.72x3.76x1.76mm)Package

Parameter	Range	Unit
Directivity	Omni-directional	N/A
Signal to Noise Ratio (SNR)	57 (f _{in} =1kHz)	dB
Sensitivity	-27~-21(1kHz, 94dB SPL)	dBFS
Total Harmonic Distortion+ Noise (THD+N)	5 (115dB SPL ,f _{in} =1kHz) Max.	%

MMIC0044737M2T (4.72x3.76x1.15mm)Package		
Parameter	Range	Unit
Directivity	Omni-directional	N/A
Signal to Noise Ratio (SNR)	55~59(@1kHz)	dB
Sensitivity	-46~-38(@1kHz, 94dB SPL)	dBFS
Total Harmonic Distortion+ Noise (THD+N)	(At 100dB SPL)THD<1 (At 115dB SPL)THD \leq 10	%

CROSS-SECTION

